

# BGF105

SIM Card Interface Filter and ESD Protection

Small Signal Discretes



Never stop thinking

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**BGF105**

**Revision History: 2007-11-22, V2.1**

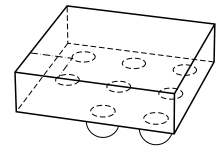
**Previous Version: 2007-10-31, V2.0**

<b>Page</b>	<b>Subjects (major changes since last revision)</b>
4	<b>Figure 1</b> replaced with schematic, 2nd schematic deleted
6	<b>Figure 3</b> background colour changed to white
6	<b>Figure 4</b> updated
7	<b>Figure 5</b> updated
5	<b>Table 2</b> typical values added

## BGF105

### Features

- ESD protection circuit and interface filter for SIM cards
- Integrated ESD protection of external pins up to 15 kV contact discharge according to IEC61000-4-2
- Wafer level package with SnAgCu solder balls
- 500  $\mu\text{m}$  solder ball pitch
- RoHS and WEEE compliant package

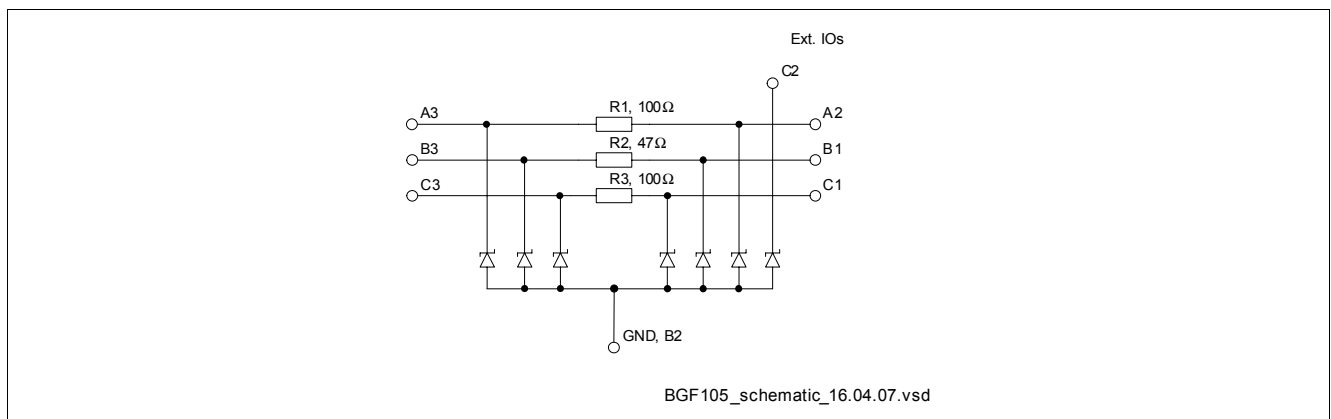


S-WLP-8-5



### Description

The BGF105 is an ESD protection circuit and filtering interface for SIM cards. The external pins are protected against ESD up to 15 kV contact discharge according to IEC61000-4-2. The wafer level package is a green leadfree package with a size of only 1.45 mm x 1.45 mm and a total height of 0.65 mm



**Figure 1** BGF105 schematic

Type	Package	Marking	Chip
BGF105	WLP-8-5	BGF105	N0721

**Table 1** Maximum Ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Voltage at all pins to GND	$V_P$	0	–	5	V	–
Operating temperature range	$T_{OP}$	-40	–	+85	$^{\circ}\text{C}$	–
Storage temperature range	$T_{STG}$	-65	–	+150	$^{\circ}\text{C}$	–
Summed up into power for all pins	$P_{in}$	–	–	60	mW	$T_S < 70\text{ }^{\circ}\text{C}$

#### Electrostatic Discharge According to IEC61000-4-2

Contact discharge at internal pins A3, B3, C3	$V_{ESD}$	-2	–	2	kV	–
Contact discharge at external pins A2, B1, C1, C2	$V_{ESD}$	-15	–	15	kV	–

Table 2 Electrical Characteristics<sup>1)</sup>

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Resistors $R_1, R_3$	$R_{1,3}$	80	100	120	$\Omega$	–
Resistor $R_2$	$R_2$	37.6	47	56.4	$\Omega$	–
Reverse current of ESD protection diodes	$I_R$	–	1	100	nA	$V = 3\text{ V}$
		–	2	1000	nA	$V = 5\text{ V}$
Breakdown voltage of ESD diodes	$V_{(BR)}$	6.5	7.8	–	V	$I_{(BR)} = 1\text{ mA}$
Line capacitance Capacitance of all lines to GND	$C_T$	–	17.6	20	pF	$V = 0\text{ V}$

1) at  $T_A = 25\text{ }^\circ\text{C}$

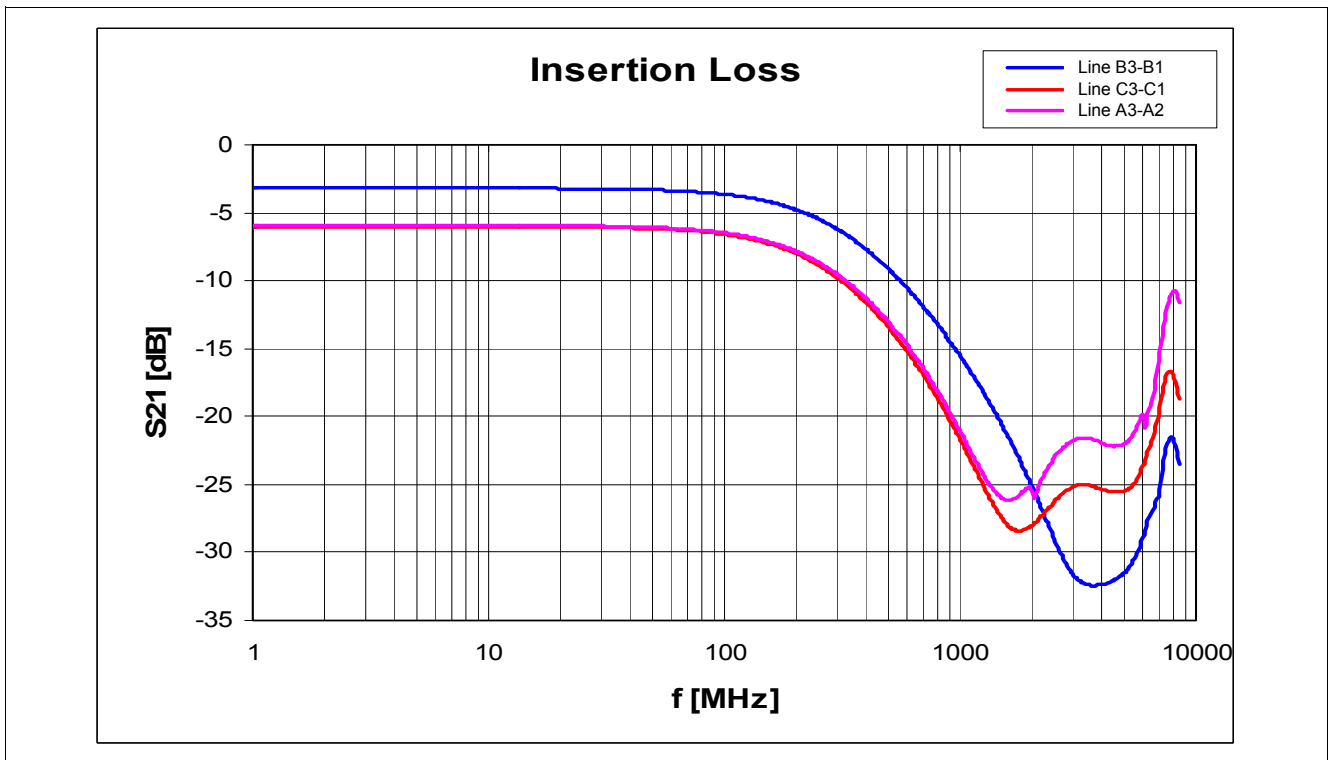


Figure 2 Insertion Loss

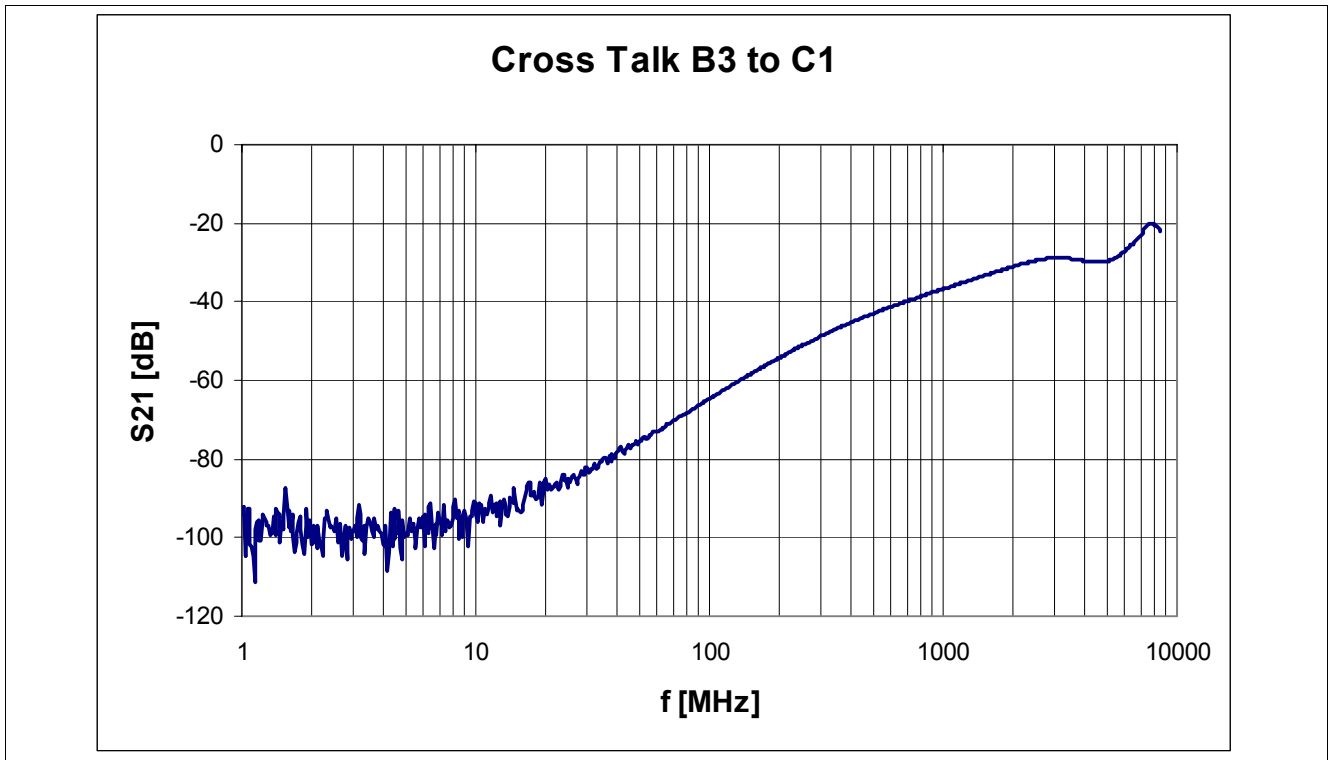


Figure 3 Cross Talk

Package Outlines

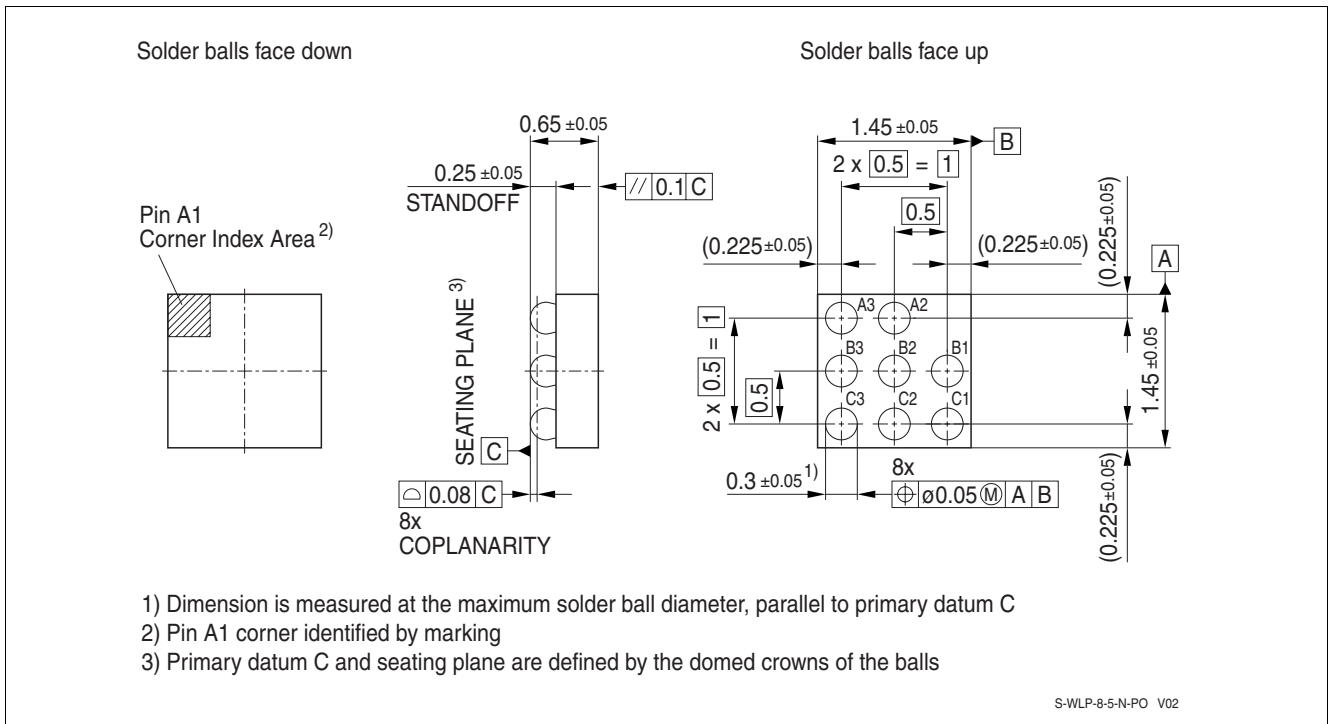
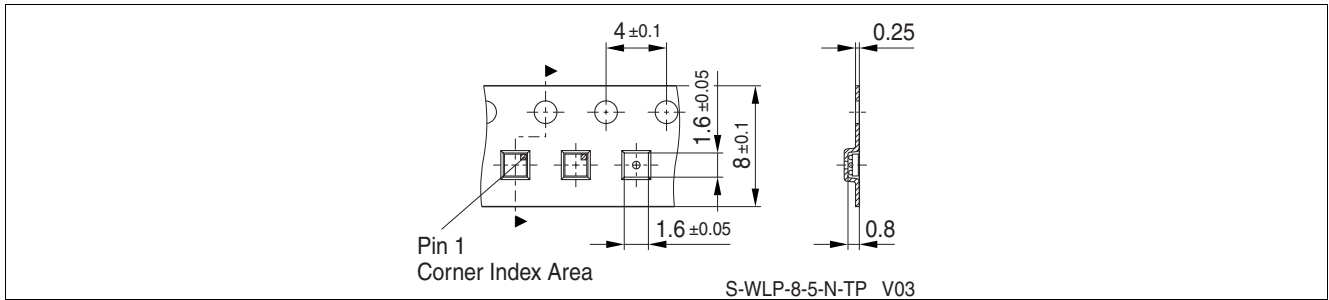


Figure 4 WLP-8-5 (Wafer Level Package)

**Tape for BGF105**



**Figure 5 Tape for BGF105 / WLP-8-5**

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